Cooling Techniques For Electronic Equipment

The Eurotherm Committee has chosen Thermal Management of Electronic Systems as the subject of its 29th Seminar, at Delft University of Technology, the Netherlands, 14-16 June 1993. This volume constitutes the proceedings of the Seminar. Thermal Management is but one of the several critical topics in the design of electronic systems. However, as a result of the combined effects of increasing heat fluxes, miniaturisation and the striving for zero defects, preferably in less time and at a lower cost than before, thermal management has become an increasingly tough challenge. Therefore, it is being increasingly recognised that cooling requirements could eventually hamper the technical progress in miniaturisation. It might be argued that we are on the verge of a revolution in thermal management techniques. Previously, a packaging engineer had no way of predicting the tempera tures of critical electronic parts with the required accuracy. He or she· had to rely on full-scale experiments, doubtful design rules, or worst-case estimates. This situation is going to be changed in the foreseeable future. User-friendly software tools, the acquisition and integrity of input and output data, the badly needed training mea sures, the introduction into a concurrent engineering environment: all these items will exert a heavy toll on the flexibility of the electronics industries. Fortunately, this situation is being realised at the appropriate management levels, and the interest in this seminar and the pre-conference tutorials testifies to this assertion.

Since conventional cooling techniques are increasing falling short of meeting the ever-growing cooling demands of high heat generating devices, thermal systems, and processes, advanced and innovative cooling technologies are of immense importance to deal with such high thermal management. Hence, this book covers a number of key topics related to advanced cooling approaches, their performance, and applications, including: Evaporative air cooling; Spray impingement cooling; Heat pump-based cooling; Modular cooling for photovoltaic plant; Nucleate pool boiling of refrigerants; Transient flashing spray cooling and application; Compressor cooling systems for industry. The book is aimed at a wide variety of people from graduate students and researchers to manufacturers who are involved or interested in the areas of thermal management systems, cooling technologies, and their applications.

CD-ROM contains: the limited academic version of Engineering equation solver(EES) with homework problems.

"Describes the latest techniques and real-life applications of computational fluid dynamics (CFD) and heat transfer in aeronautics, materials processing and manufacturing, electronic cooling, and environmental control. Includes new material from experienced researchers in the field. Complete with detailed equations for fluid flow and heat transfer.

Presenting contributions from renowned experts in the field, this book covers research and development in fundamental areas of heat exchangers, which include: design and theoretical development, experiments, numerical modeling and simulations. This book is intended to be a useful reference source and guide to researchers, postgraduate students, and engineers in the fields of heat exchangers, cooling, and thermal management.

The continuing trend toward miniaturization and high power density electronics results in a growing interdependency between different fields of engineering. In particular, thermal management has become essential to the design and manufacturing of most electronic systems. Heat Transfer: Thermal Management of Electronics details how engineers can use intelligent thermal design to prevent heat-related failures, increase the life expectancy of the system, and reduce emitted noise, energy consumption, cost, and time to market. Appropriate thermal management can also create a significant market differentiation, compared to similar systems. Since there are more design flexibilities in the earlier stages of product design, it would be productive to keep the thermal design in mind as early as the concept and feasibility phase. The author first provides the basic knowledge necessary to understand and solve simple electronic cooling problems. He then delves into more detail about heat transfer fundamentals to give the reader a deeper understanding of the physics of heat transfer. Next, he describes experimental and numerical techniques and tools that are used in a typical thermal design process. The book concludes with a chapter on some advanced cooling methods. With its comprehensive coverage of thermal design, this book can help all engineers to develop the necessary expertise in thermal management of electronics and move a step closer to being a multidisciplinary engineer.

Chemical Engineering Design
Design Methods and Charts for Heat Exchange Devices Applicable to Indirect Cooling of Electronic Assemblies
High Temperature Electronics
Prudent Practices in the Laboratory
A Practical Approach with EES CD
Learning Through Discovery
Electronics Cooling
Principles, Practice and Economics of Plant and Process Design
Design Manual of Natural Methods of Cooling Electronic Equipment
Heat Transfer

Most introductory textbooks in electronics focus on the theory while leaving the practical aspects to be covered in laboratory courses. However, the sooner such matters are introduced, the better able students will be to include such important concerns as parasitic effects and reliability at the very earliest stages of design. This philosophy has kept Electronic Components and Technology thriving for two decades, and this completely updated third edition continues the approach with a more international outlook. Not only does this textbook introduce the properties, behavior, fabrication, and use of electronic components, it also helps students grasp and apply sound engineering practice by incorporating in-depth discussions on topics such as safety and reliability. The author employs a holistic treatment that clearly demonstrates how electronic components and subsystems work together, reinforcing the concepts with numerous examples, case studies, problems, illustrations, and objectives. This edition was updated to reflect advances and changes to industrial practice, including packaging technologies, digital oscilloscopes, lead-free solders, and new battery technologies. Additionally, the text's scope now extends to include terminology and standards used worldwide. Including coverage of topics often ignored in other textbooks on the subject, Electronic Components and Technology, Third Edition encourages students to be better, more thoughtful designers and prepares them with current industrial practices.

This book deals with the analysis of various types of vibration environments that can lead to the failure of electronic systems or components.

Details infallible techniques for designing electronic hardware to withstand severe thermal environments. Using both SI and English units throughout, it presents methods for the development of various reliable electronic systems without the need of high-speed computers. It also offers mathematical modeling applications, using analog resistor networks, to provide the breakup of complex systems into numerous individual thermal resistors and nodes for those who prefer high-speed digital computer solutions to thermal problems.

This book is essential for anyone involved in the design of high-performance heat exchangers or heat devices, also known as "second generation heat transfer technology." Enhanced surfaces are geometrics with special shapes that promote much higher rates of heat transfer than smooth or plain surfaces. This revision presents the subject matter just beyond the introductory level and traces the advancement of heat transfer research in areas such as integral-fin and micro-fin tubes, complex plate-fin geometries, and micro-channels for single-phase and two-phase applications.

"This is teaching at its best!" --Hans Camenzind, inventor of the 555 timer (the world's most successful integrated circuit), and author of Much Ado About Almost Nothing: Man's Encounter with the Electron (Booklocker.com) "A fabulous book: well written, well paced, fun, and informative. I also love the sense of humor. It's very good at disarming the fear. And it's gorgeous. I'll be recommending this book highly." --Tom Igoe, author of Physical Computing and Making Things Talk Want to learn the fundamentals of electronics in a fun, hands-on way? With Make: Electronics, you'll start working on real projects as soon as you crack open the book. Explore all of the key components and essential principles through a series of fascinating experiments. You'll build the circuits first, then learn the theory behind them! Build working devices, from simple to complex You'll start with the basics and then move on to more complicated projects. Go from switching circuits to integrated circuits, and from simple alarms to programmable microcontrollers. Step-by-step instructions and more than 500 full-color photographs and illustrations will help you use -- and understand -- electronics concepts and techniques. Discover by breaking things: experiment with components and learn from failure Set up a tricked-out project space: make a work area at home, equipped with the tools and parts you'll need Learn about key electronic components and their functions within a circuit Create an intrusion alarm, holiday lights, wearable electronic jewelry, audio processors, a reflex tester, and a combination lock Build an autonomous robot cart that can sense its environment and avoid obstacles Get clear, easy-to-understand explanations of what you're doing and why

Featuring contributions from the renowned researchers and academicians in the field, this book covers key conventional and emerging cooling techniques and coolants for electronics cooling. It includes following thematic topics: - Cooling approaches and coolants - Boiling and phase change-based technologies - Heat pipes-based cooling - Microchannels cooling systems - Heat loop cooling technology - Nanofluids as coolants - Theoretical development for the junction temperature of package chips. This book is intended to be a reference source and guide to researchers, engineers, postgraduate students, and academicians in the fields of thermal management and cooling technologies as well as for people in the electronics and semiconductors industries.

Guide Manual of Cooling Methods for Electronic Equipment
Proceedings of EUROTHERM Seminar 29, 14-16 June 1993, Delft, The Netherlands
Principles of Enhanced Heat Transfer
Electronic Components and Technology
Advanced Thermal Design of Electronic Equipment
Designing Electronic Product Enclosures
Cooling Techniques for Electronic Equipment
Applied Computational Fluid Dynamics
Heat Pipes
Structural Dynamics of Electronic and Photonic Systems

The proposed book will offer comprehensive and versatile methodologies and recommendations on how to determine dynamic characteristics of typical micro- and opto-electronic structural elements (printed circuit boards, solder joints, heavy devices, etc.) and how to design a viable and reliable structure that would be able to withstand high-level dynamic loading. Particular attention will be given to portable devices and systems designed for operation in harsh environments (such as automotive, aerospace, military, etc.) In-depth discussion from a mechanical engineer's viewpoint will be conducted to the key components' level as well as the whole device level. Both theoretical (analytical and computer-aided) and experimental methods of analysis will be addressed. The authors will identify how the failure control parameters (e.g. displacement, strain and stress) of the vulnerable components may be affected by the external vibration or shock loading, as well as by the internal parameters of the infrastructure of the device. Guidelines for material selection, effective protection and test methods will be developed for engineering practice.

This book gives information and guidance on important subjects. It presents the major and efficient applications for efficient insulation materials. The book is divided into two parts. Part I discusses ecological insulation materials. In this part, the three sub-subjects are drafting, Unconventional insulation materials, Jute-Based Insulation Material, and Possible Applications of Corn Cob as a Raw Insulation Material. Part II: discusses Practical Applying and Performance of Insulation Materials (case studies), where three sub-subjects are drafting seismic aspects of the application of thermal insulation boards beneath the building's foundations, flammability of bio-based rigid polyurethane foam thermal insulation, and the review of some commonly used methods and techniques to measure the thermal conductivity of insulation materials.

The development of electronics that can operate at high temperatures has been identified as a critical technology for the next century. Increasingly, engineers will be called upon to design avionics, automotive, and geophysical electronic systems requiring components and packaging reliable to 200 °C and beyond. Until now, however, they have had no single resource on high temperature electronics to assist them. Such a resource is critically needed, since the design and manufacture of electronic components have now made it possible to design electronic systems that will operate reliably above the traditional temperature limit of 125 °C. However, successful system development efforts hinge on a firm understanding of the fundamentals of semiconductor physics and device processing, materials selection, package design, and thermal management, together with a knowledge of the intended application environments. High Temperature Electronics brings together this essential information and presents it for the first time in a unified way. Packaging and device engineers and technologists will find this book required reading for its coverage of the techniques and tradeoffs involved in materials selection, design, and thermal management and for its presentation of best design practices using actual fielded systems as examples. In addition, professors and students will find this book suitable for graduate-level courses because of its detailed level of explanation and its coverage of fundamental scientific concepts. Experts from the field of high temperature electronics have contributed to nine chapters covering topics ranging from semiconductor device selection to testing and final assembly.

This book presents contributions from renowned experts addressing research and development related to the two important areas of heat exchangers, which are advanced features and applications. This book is intended to be a useful source of information for researchers, postgraduate students, academics, and engineers working in the field of heat exchangers research and development.

To celebrate Professor Avi Bar-Cohen's 65th birthday, this unique volume is a collection of recent advances and emerging research from various luminaries and experts in the field. Cutting-edge technologies and research related to thermal management and thermal packaging of micro- and nanoelectronics are covered, including enhanced heat transfer, heat sinks, liquid cooling, phase change materials, synthetic jets, computational heat transfer, electronics reliability, 3D packaging, thermoelectrics, data centers, and solid state lighting. This book can be used by researchers and practitioners of thermal engineering to gain insight into next generation thermal packaging solutions. It is an excellent reference text for graduate-level courses in heat transfer and electronics packaging. Contents:A Review of Cooling Road Maps for 3D Chip Packages (Dereje Agonafer)Thermal Performance Mapping of Direct Liquid Cooled 3D Chip Stacks (Karl J L Geisler and Avram Bar-Cohen)Dynamic Thermal Management Considering Accurate Temperature-Leakage Interdependency (Bing Shi and Ankur Srivastava)Energy Reduction and Performance Maximization Through Improved Cooling (David Copeland)Optimal Choice of Heat Sinks from an Industrial Point of View (Clemens J M Lasance)Synthetic Jets for Heat Transfer Augmentation in Microelectronics Systems (Mehmet Arik and Enes Tamdogan)Recent Advance in Thermoelectric Devices for Electronics Cooling (Peng Wang)Energy Efficient Solid-State Cooling for Hot Spot Removal (Kazuaki Yazawa, Andrei Fedorov, Yogendra Joshi and Ali Shakouri)An Overview of the Use of Phase Change Materials for the Thermal Management of Transient Portable Electronics: Benefits and Challenges (Amy S Fleischer)Estimation of Cooling Performance of Phase Change Material (PCM) Module (Masaru Ishizuka and Tomoyuki Hatakeyama)Optimization Under Uncertainty for Electronics Cooling Design (Karthik K Bodla, Jayathi Y Murthy and Suresh V Garimella)Hydrophilic CNT-Sintered Copper Composite Wick for Enhanced Cooling (Glen A Powell, Anuradha Bulusu, Justin A Weibel, Sungwon S Kim, Suresh V Garimella and Timothy S Fisher)A Cabinet Level Thermal Test Vehicle to Evaluate Hybrid Double-Sided Cooling Schemes (Qihong Nie and Yogendra Joshi)Energy Efficiency and Reliability Risk Mitigation of Data Centers Through Prognostics and Health Management (Jun Dai, Michael Ohadi and Michael Pecht)Damage Pre-Cursors Based Assessment of Accrued Thermomechanical Damage and Remaining Useful Life in Field Deployed Electronics (Pradeep Lall, Mahendra Harsha, Kai Goebel and Jim Jones)Towards Embedded Cooling — Gen 3 Thermal Packaging Technology (Avram Bar-Cohen) Readership: Researchers, practitioners, and postgraduates in mechanical engineering, nanoelectronics, computer engineering, and electrical & electronic engineering. Keywords:Electronics Cooling;Electronics Packaging;Thermal Management;Thermal Sciences;Electronics Reliability;Thermoelectrics;Computational Heat Transfer;Liquid Cooling

This text explains the process of the design of product electronic enclosures. These products typically contain a printed circuit board. The text takes the reader from the original idea for a product, through the shipment in quantity to a customer. For the product enclosure designer, this proceeds through design layout, material selection, prototype building, testing, and ongoing design improvement. The book presents a substantive and lucid treatment of the structural, thermal, user-interface, assembly, quality control, and cost considerations of the product enclosure. Of special note is a discussion on the regulatory issues involved with the design of a product. A main thrust of the text is on the "commercialization" aspects of electronic products, that is, when an enclosure is needed for the product to meet environmental and certification requirements globally. The book targets the broadest audience tasked to design/manufacture an enclosure, from mechanical/industrial engineers to designers and technicians. While the intent of the text is not to provide a complete understanding of relevant physical phenomena addressed (strength of materials, shock and vibration, heat transfer), the book provides a ready reference on how and where these key properties may be considered in the design of most electronic enclosures. Elucidates successful enclosure design for electronic products, defining the design team and the definition of success Explains the processes for building enclosures, including printed circuit board layout (mechanical considerations) and optimal object placement, structural considerations, material selection, and user interface design Includes treatment of serviceability, product environments, standards and testing, cooling techniques as well as guidelines for Electromagnetic Compliance (EMC) standards and testing required to pass FCC/CE Reinforces design concepts presented with relevant solved problems

Theory, Design and Applications
Advanced Cooling Technologies and Applications
Vibration Analysis for Electronic Equipment
Techniques for the Cooling Design of Airborne Electronic Equipment
Preventing Thermal Cycling and Vibration Failures in Electronic Equipment
Thermal Management of Electronic Systems
Advanced Features and Applications
Air Cooling Technology for Electronic Equipment
Heat Exchangers
Thermal Management of Electronics

With today's high density, high performance electronic systems, packaging and more specifically thermal engineering has become the critical factor that limits on-time product introduction and reliability in the field. This book serves as a reference for engineers who must predict the thermal performance of a company's latest product as well as the technicians who must quickly solve the problem of an overheating chip in a product that is already on the shelves.

Heat Pipes, 6th Edition, takes a highly practical approach to the design and selection of heat pipes, making it an essential guide for practicing engineers and an ideal text for postgraduate students. This new edition has been revised to include new information on the underlying theory of heat pipes and heat transfer, and features fully updated applications, new data sections, and updated chapters on design and electronics cooling. The book is a useful reference for those with experience and an accessible introduction for those approaching the topic for the first time. Contains all information required to design and manufacture a heat pipe Suitable for use as a professional reference and graduate text Revised with greater coverage of key electronic cooling applications

Electronic technology is developing rapidly and, with it, the problems associated with the cooling of microelectronic equipment are becoming increasingly complex. So much so that it is necessary for experts in the fluid and thermal sciences to become involved with the cooling problem. Such thoughts as these led to an approach to leading specialists with a request to contribute to the present book. Cooling of Electronic Systems presents the technical progress achieved in the fundamentals of the thermal management of electronic systems and thermal strategies for the design of microelectronic equipment. The book starts with an introduction to the cooling of electronic systems, involving such topics as trends in computer system cooling, the cooling of high performance computers, thermal design of microelectronic components, natural and forced convection cooling, cooling by impinging air and liquid jets, thermal control systems for high speed computers, together with a detailed review of advances in manufacturing and assembly technology. Following this, practical methods for the determination of the parameters required for the thermal analysis of electronic systems and the accurate prediction of temperature in consumer electronics. Cooling of Electronic Systems is currently the most up-to-date book on the thermal management of electronic and microelectronic equipment, and the subject is presented by eminent scientists and experts in the field. Vital reading for all designers of modern, high-speed computers.

This book deals with the packaging of electronic equipment to prevent damage from vibration and exposure to large variations in temperature.

Clear your bookcase of references containing bits and pieces of useful information and replace them with this thorough, single-volume guide to thermal analysis. Air Cooling Technology for Electronic Equipment is a helpful, practical resource that answers questions frequently asked by thermal and packaging engineers grappling with today's demand for increased thermal control in electronics. Superbly organized for quick reference, the book dedicates each chapter to answering fundamental questions, such as: What is the optimal spacing between the printed circuit boards? What is a good estimate of the heat transfer coefficient and the associate pressure drop for forced convection over package arrays? How are heat transfer and fluid flow characteristics in the entrance region different from those in the fully developed region? What is the effect of substrate conduction on convection cooling? The chapters, written by engineers and engineering educators who are experts in electronic cooling, are packed with details and present the latest developments in air cooling techniques and thermal design guidelines. They provide problem-solving analyses that are jargon-free, straightforward, and easy to understand. Air Cooling Technology for Electronic Equipment is a handy source of technical information for anyone who wants to get the most out of air cooling.

Part I: Process design -- Introduction to design -- Process flowsheet development -- Utilities and energy efficient design -- Process simulation -- Instrumentation and process control -- Materials of construction -- Capital cost estimating -- Estimating revenues and production costs -- Economic evaluation of projects -- Safety and loss prevention -- General site considerations -- Optimization in design -- Part II: Plant design -- Equipment selection, specification and design -- Design of pressure vessels -- Design of reactors and mixers -- Separation of fluids -- Separation columns (distillation, absorption and extraction) -- Specification and design of solids-handling equipment -- Heat transfer equipment -- Transport and storage of fluids.

Materials for High-Density Electronic Packaging and Interconnection
Advances and Emerging Research
Design Manual of Methods of Forced Air Cooling Electronic Equipment
Cooling of Electronic Systems
Design, Experiment and Simulation
Thermal Computations for Electronic Equipment
Cooling Electronic Equipment
Handbook of Electronic Package Design
Insulation Materials in Context of Sustainability
Handling and Management of Chemical Hazards, Updated Version

Prudent Practices in the Laboratory--the book that has served for decades as the standard for chemical laboratory safety practice--now features updates and new topics. This revised edition has an expanded chapter on chemical management and delves into new areas, such as nanotechnology, laboratory security, and emergency planning. Developed by experts from academia and industry, with specialties in such areas as chemical sciences, pollution prevention, and laboratory safety, Prudent Practices in the Laboratory provides guidance on planning procedures for the handling, storage, and disposal of chemicals. The book offers prudent practices designed to promote safety and includes practical information on assessing hazards, managing chemicals, disposing of wastes, and more. Prudent Practices in the Laboratory will continue to serve as the leading source of chemical safety guidelines for people working with laboratory chemicals: research chemists, technicians, safety officers, educators, and students.

Both a handbook for practitioners and a text for use in teaching electronic packaging concepts, guidelines, and techniques. The treatment begins with an overview of the electronics design process and proceeds to examine the levels of electronic packaging and the fundamental issues in the development

In a field where change and growth is inevitable, new electronic packaging problems continually arise. Smaller, more powerful devices are prone to overheating, causing intermittent system failures, corrupted signals, lower MTBF, and outright system failure. Since convection cooling is the heat transfer path most engineers take to deal with thermal problems, it is appropriate to gain as much understanding about the underlying mechanisms of fluid motion as possible. Thermal Design of Electronic Equipment is the only book that specifically targets the formulas used by electronic packaging and thermal engineers. It presents heat transfer equations dealing with polyalphaolephin (PAO), silicone oils, perfluorocarbons, and silicate ester-based liquids. Instead of relying on theoretical expressions and text explanations, the author presents empirical formulas and practical techniques that allow you to quickly solve nearly any thermal engineering problem in electronic packaging.

Forced-air Cooling Techniques for Electronic Equipment
Thermal Design of Electronic Equipment
Cooling of Microelectronic and Nanoelectronic Equipment
Make: Electronics
Investigation of Methods of Fresh Water Cooling Electronic Equipment
Interim Report